

HMC349LP4C

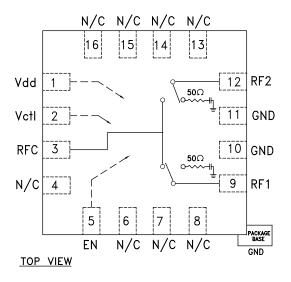
HIGH ISOLATION SPDT NON-REFLECTIVE SWITCH, DC - 4.0 GHz

Typical Applications

The HMC349LP4C is ideal for:

- Basestation Infrastructure
- MMDS & 3.5 GHz WLL
- CATV/CMTS
- Test Instrumentation

Functional Diagram



Features

High Isolation: 67 dB @ 1 GHz

62 dB @ 2 GHz

Single Positive Control: 0/+5V

+52 dBm Input IP3

Non-Reflective Design

All Off State

16 mm² Leadless QFN SMT Package

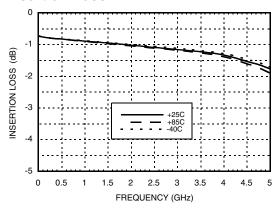
General Description

The HMC349LP4C is a high isolation non-reflective DC to 4 GHz GaAs MESFET SPDT switch in a low cost leadless surface mount package. The switch is ideal for cellular/PCS/3G basestation applications yielding 60 to 65 dB isolation, low 0.9 dB insertion loss and +52 dBm input IP3. Power handling is excellent up through the 3.5 GHz WLL band with the switch offering a P1dB compression point of +31 dBm. On-chip circuitry allows a single positive voltage control of 0/+5 Volts at very low DC currents. An enable input (EN) set to logic high will put the switch in an "all off" state.

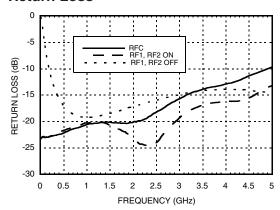
Electrical Specifications, $T_{\Delta} = +25^{\circ}$ C, Vctl = 0/+5 Vdc, Vdd = +5 Vdc, 50 Ohm System

Parameter	Frequency	Min.	Тур.	Max.	Units
Insertion Loss	DC - 1.0 GHz DC - 2.0 GHz DC - 3.0 GHz DC - 4.0 GHz		0.9 1.0 1.2 1.4	1.2 1.3 1.5 1.7	dB dB dB dB
Isolation (RFC to RF1/RF2)	DC - 1.0 GHz DC - 4.0 GHz	60 55	67 62		dB dB
Return Loss (On State)	DC - 2.0 GHz DC - 3.0 GHz DC - 4.0 GHz		20 15 13		dB dB dB
Return Loss (Off State)	0.5 - 4.0 GHz		15		dB
Input Power for 1 dB Compression	0.25 - 4.0 GHz	27	31		dBm
Input Third Order Intercept (Two-Tone Input Power = +7 dBm Each Tone)	0.25 - 1.0 GHz 1.0 - 2.0 GHz 2.0 - 3.0 GHz 3.0 - 4.0 GHz		52 50 49 46		dBm dBm dBm dBm
Switching Speed	DC - 4.0 GHz				
tRISE, tFALL (10/90% RF) tON, tOFF (50% CTL to 10/90% RF)			50 120		ns ns

Insertion Loss

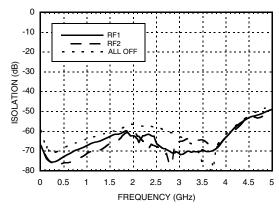


Return Loss

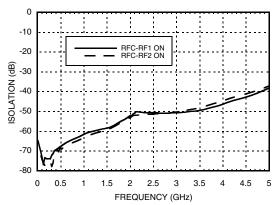


Note: RFC is reflective in "all off" state.

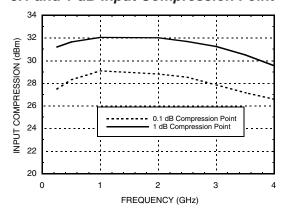
Isolation Between Ports RFC and RF1 / RF2



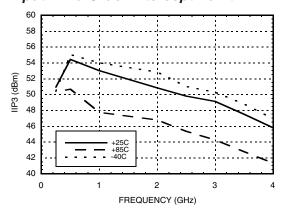
Isolation Between Ports RF1 and RF2



0.1 and 1 dB Input Compression Point



Input Third Order Intercept Point





Absolute Maximum Ratings

RF Input Power (Vctl = 0V/+5V) (0.25 - 4 GHz)	+30 dBm (T = +85 °C)
Supply Voltage Range (Vdd)	+7 Vdc
Control Voltage Range (Vctl)	-1V to Vdd +1V
Hot Switch Power Level (Vdd = +5V)	+30 dBm
Channel Temperature	150 °C
Continuous Pdiss (T = 85 °C) (derate 12 mW/°C above 85 °C)	0.75 W
Thermal Resistance	87 °C/W
Storage Temperature	-65 to +150 °C
Operating Temperature	-40 to +85 °C

Note: DC blocking capacitors are required at ports RFC, RF1 and RF2. Their value will determine the lowest transmission frequency.

TTL/CMOS Control Voltages

State	Bias Condition	
Low	0 to +0.8 Vdc @ <1 μA Typical	
High	+2.0 to +5.0 Vdc @ 30 μA Typical	

Truth Table

Control Input		Signal Path State		
Vctl	EN	RFC - RF1	RFC - RF2	
Low	Low	OFF	ON	
High	Low	ON	OFF	
Low	High	OFF	OFF	
High	High	OFF	OFF	

Bias Voltage & Current

Vdd Range = +5.0 Vdc ± 10%			
Vdd (Vdc)	ldd (Typ.) (mA)	Idd (Max.) (mA)	
+5.0	2.3	5.0	

0.028 0.70 0.020 0.50

PIN 1

EXPOSED GROUND PADDLE MUST BE CONNECTED TO RF/DC GROUND

Outline Drawing

161 4.10 3.90 .015 [0.39] .015 [0.39] .011 [0.27] .015 [0.39] .015

-C-

BOTTOM VIEW

- PACKAGE BODY MATERIAL: LOW STRESS INJECTION MOLDED PLASTIC SILICA AND SILICON IMPREGNATED.
- 2. LEADFRAME MATERIAL: COPPER ALLOY
- 3. LEADFRAME PLATING: Sn/Pb SOLDER
- 4. DIMENSIONS ARE IN INCHES [MILLIMETERS].

DIMENSION DOES NOT INCLUDE MOLDFLASH OF 0.15mm PER SIDE.

- 6. DIMENSION DOES NOT INCLUDE MOLDFLASH OF 0.25mm PER SIDE.
- TO PCB RF GROUND.

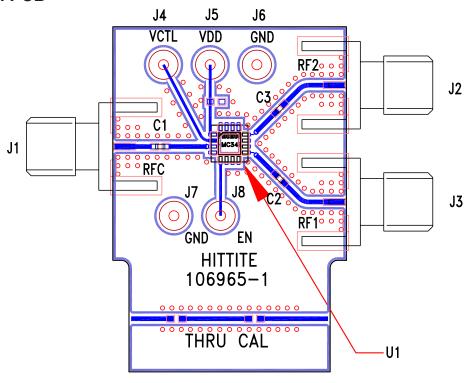


Pin Descriptions

Pin Number	Function	Description	Interface Schematic
1	Vdd	Supply Voltage.	
2	Vctl	Control input. See truth and control voltage tables.	Vctl 0 Vdd 134K
3, 9, 12	RFC, RF1, RF2	These pins are DC coupled and matched to 50 Ohms. Blocking capacitors are required.	
4, 6, 7, 8, 13, 14, 15, 16	N/C	No connection. These pins may be connected to RF ground. Performance will not be affected.	
5	EN	Enable. See truth and control voltage tables.	○ Vdd 134K EN ○ ○ ○ ○ ○ ○ ○ ○ ○ ○ ○ ○ ○ ○ ○ ○ ○ ○ ○
10, 11	GND	Package bottom must also be connected to PCB RF ground.	



Evaluation PCB



List of Material for Evaluation PCB 106975*

Item	Description	
J1 - J3	PC Mount SMA RF Connector	
J4 - J8	DC Pin	
C1 - C3	100 pF Capacitor, 0402 Pkg.	
U1	HMC349LP4C SPDT Switch	
PCB**	106965 Evaluation PCB	
** Circuit Board Material: Rogers 4350		

^{*} Reference this number when ordering complete evaluation PCB.

The circuit board used in the final application should be generated with proper RF circuit design techniques. Signal lines at the RF port should have 50 ohm impedance and the package ground leads and backside ground slug should be connected directly to the ground plane similar to that shown above. The evaluation circuit board shown above is available from Hittite Microwave Corporation upon request.



v00.0304

SWITCHES - SMT



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Notes: